

# IMBI-QM57

## Intel QM57 Advance Mini-ITX Board Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation <b>Comment: <u>Four temperature point need improving</u></b>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	1
Defect Unsolved	0	0	0	1

Issue date

2010 / 10 / 14

Approval

Jansin Lee

Test Engineer

Allen Hsu

## Sample Configuration & Quantity Under Test

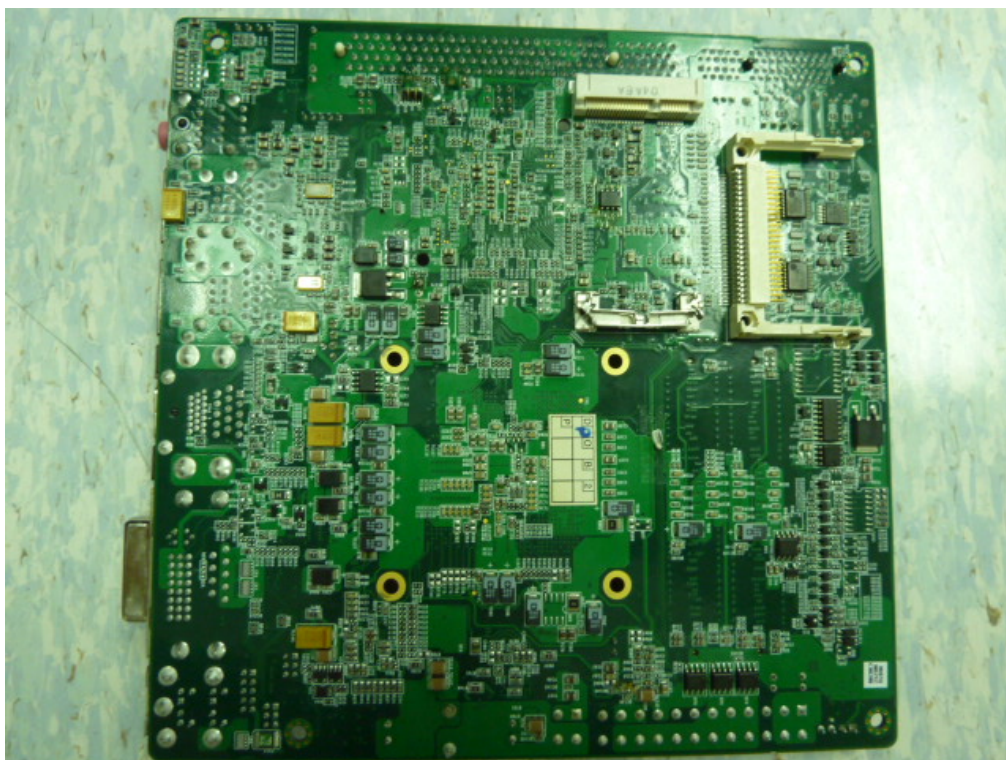
- Model name : IMBI-QM57
- CPU Board: IMBI-QM57 Rev A0.3
- Carrier Board: N/A
- CPU: Intel Core I7 CPU 620M @2.67GHz / 32nm / PQI 2400 MHz
- Memory: DSL DDR3 SO-DIMM / 1066 2GB / ELPIDA J1108BDSE-DJ-F \*2
- HDD: Seagate 3.5" SATA H.D 160GB / 7200 RPM / ST3160811AS
- BIOS : IMBI-QM57 A1.0 – 09/06/2010
- Test Software: Windows XP sp3 / Run Prime95 v26.01
- AT Power Supply: Delta ATX Power 350W GPS-350EB-102A
- Cooler:



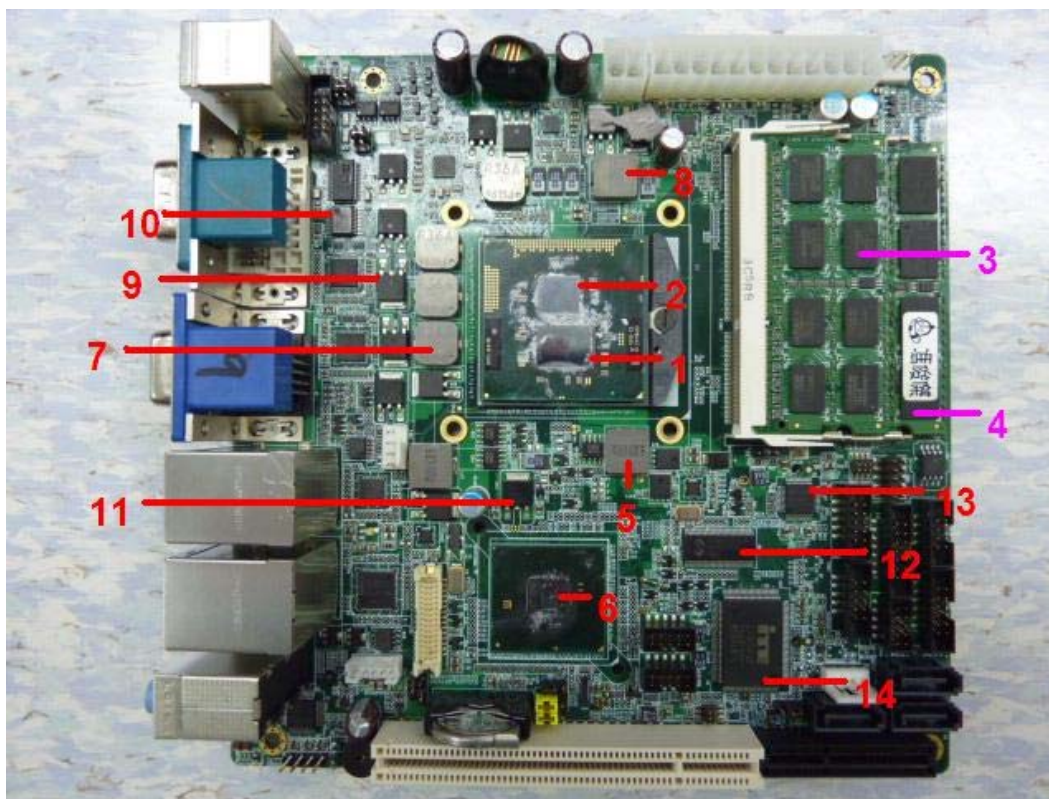
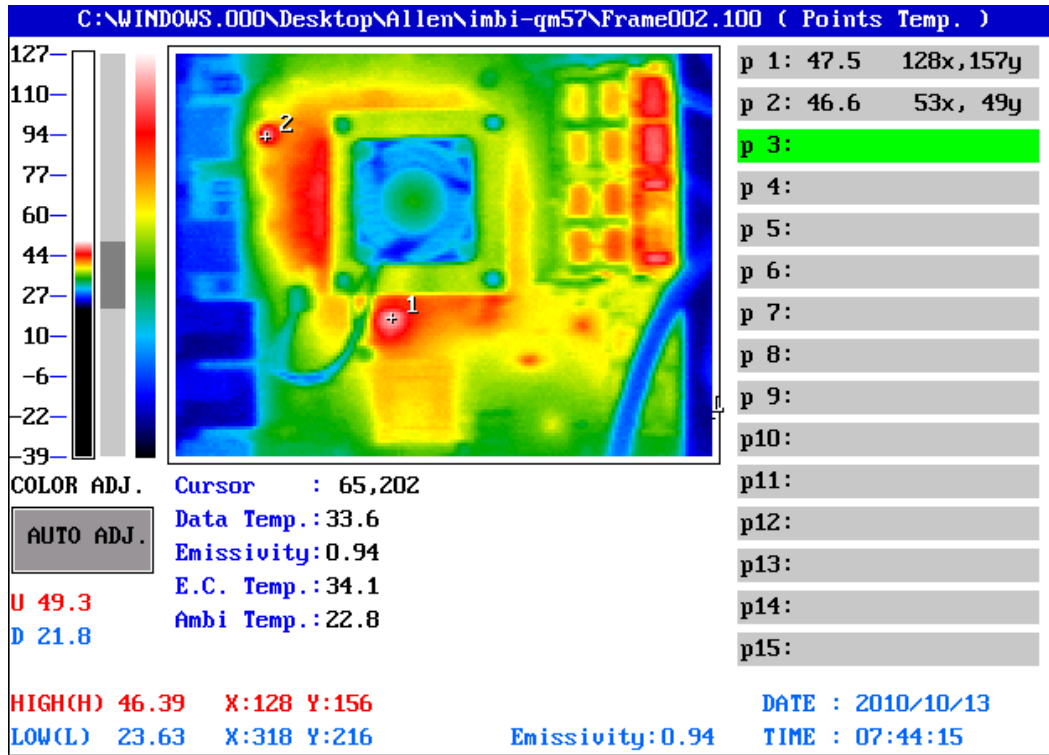
## Thermal Image Analysis

1. Test Date: 10/14/2010
2. Test Product: IMBI-QM57
3. Test Site: AAEON QA Internal Lab.
4. Temperature Measurement:
  1. GRAPHTEC midi LOGGER TYPE - GL200
  2. IR Scanner: Infrared Camera  
NIPPON AVIONICS CO., LTD.  
Model: TVS-100  
Date of Calibration: 08/10/2010  
Serial Number: 0179L2746
5. Test Condition:  
Component Side-1 (Test by TVS-100 ): 22.6°C With cooler  
Component Side-2 (Test by TVS-100 ): 23.2°C With cooler
6. Test Software:  
Windows XP sp3 / Run Prime 95 v26.01
7. Take Picture Time:  
After power on 2 hours

### Temperature Profile Test:



**Component Side-1:**



Red line – it's front side

Pink line – it's rear side

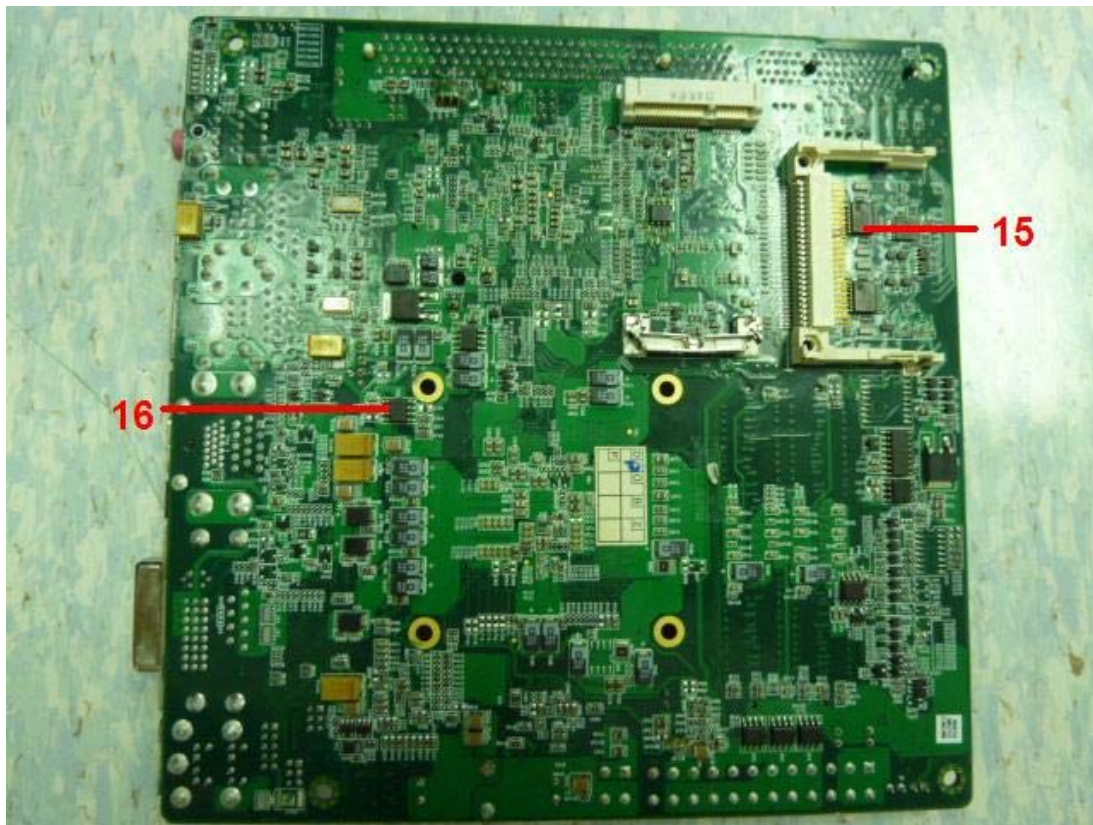
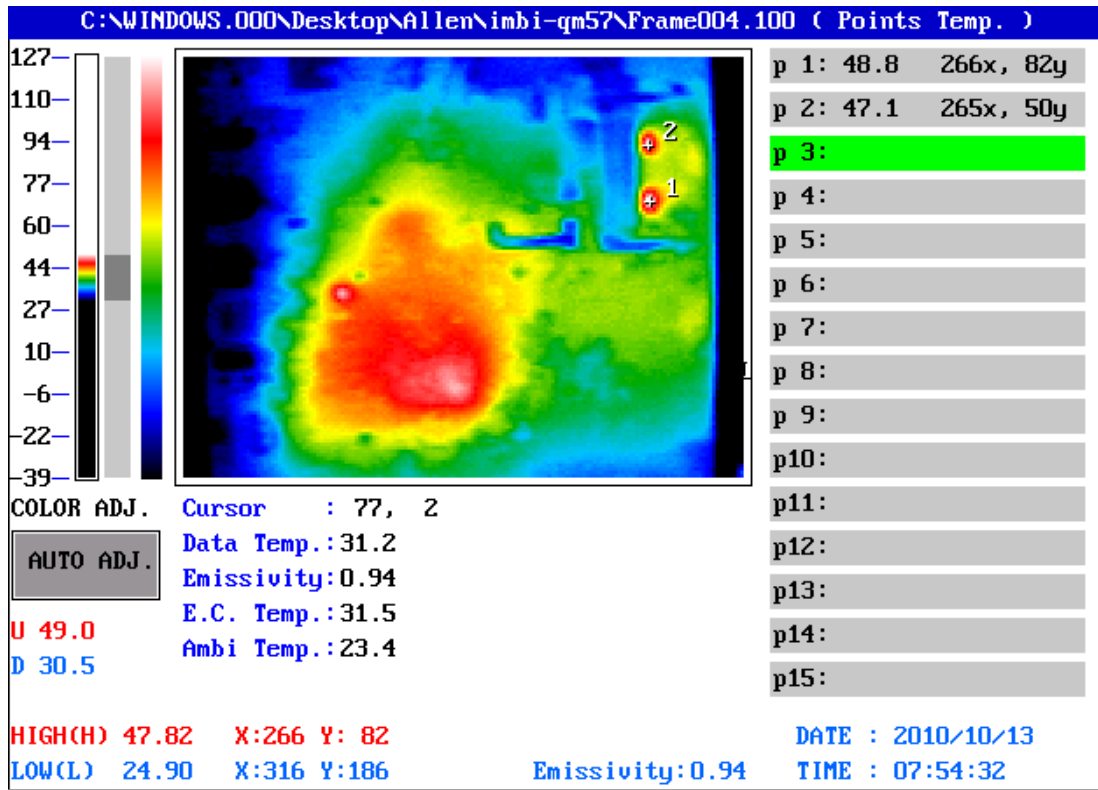
Using GRAPHTEC midi LOGGER TYPE - GL200 test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				22.6°C	60°C	
1	CPU Core1	Intel Core I7 CPU 620M @2.67GHz / 32nm / PQI 2400 MHz	105	60.2	97.6	
2	CPU Core2	Intel Core I7 CPU 620M @2.67GHz / 32nm / PQI 2400 MHz	105	62.4	99.8	
3	RAM1	DSL DDR3 SO-DIMM / 1066 2GB / ELPIDA J1108BDSE-DJ-F	95	46.7	84.1	
4	RAM2	DSL DDR3 SO-DIMM / 1066 2GB / ELPIDA J1108BDSE-DJ-F	95	48.7	86.1	
5	L5	(TF)COIL.0.56uH.Irms=25A.Isat=40A.20%.SMD(11.5x10.3x4.0).2pin.RDC=1.8m Ohm.GOTREND.GSTC104P-R56MN;EE-A061714;1211105673;TWN	125	57.4	94.8	
6	U2	(TF)IC.SMD.Chipset PCH.INTEL.BD82QM57 SLGZQ;EE-A100524;14S4BD8200;TWN	125	44.2	81.6	
7	L16	(TF)COIL.0.36uH.Irms=34A.20%.MD(11.5x10x4.0).2pin.RDC=0.76m Ohm.Panasonic.ETQP4LR36AFC;EE-A100404;1211103671;TWN	130	51.4	88.8	
8	L6	(TF)COIL.1uH.20%.SMD.11.5x10.3x4.0mm.DCR=3m ohm.Irms=18Amp.GOTREND.GSTC104P-1R0MN;EE-A070616;1211101064;TWN	125	42.6	80	
9	Q48	(TF)PWR.SMD TO-252.30V 58A.N-channel Power MOSFET.FAIRCHILD.FDD8880;EE-A061121;1315888010;TWN	150	41.2	78.6	
10	U29	(TF)IC.SMD SSOP.20Pin RS-232 Driver&Receivers.TI.GD75232DBR;EE-A010945;14S5A23200;TWN	100	46.0	83.4	
11	U12	(TF)REG.SMD.TO-252 5A Linear Regulator.Diodes.AP1084DG-13;EE-A011431;1314108412;TWN	100	52.5	89.9	
12	U6	(TF)IC.SMD.TSSOP 64P.CLOCK GENERATOR.SILEGO.SLG505YC264BTTR;EE-A081678;14S3050500;TWN	100	45.2	82.6	
13	U4	(TF)IC.SMD.LQFP 48P.PCI Express to.PATA Host Controller.JMicron.JMB368-LGGZ0A;EE-A090147;14S4036800;TWN	100	43.8	81.2	
14	U5	(TF)IC.SMD.QFP128P.Super I/O w/4 COMs.ITE.IT8781F/AX-L;EE-A081754;14S4878100;TWN	100	48.7	86.1	

Note(\*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
  - "Tm" indicates the measured Tc value under working environmental temperature within product specification.
3. Judgment Criteria:
- Fail : Tm > Tc+5°C; The measured value is over specification plus margin.
  - Margin : Tc+5 °C > Tm > Tc -10°C; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
  - Pass : Tm < Tc-10°C; The measured value is with safety margin.

Component Side-2:



**Using GRAPHTEC midi LOGGER TYPE - GL200 test**

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				23.2°C	60°C	
15	U58	(TF)IC.SMD SSOP.20Pin RS-232 Driver&Receivers.TI.GD75232DBR;EE-A010945;14S5A23 200;TWN	100	57.4	94.2	
16	U49	(TF)IC.SMD.SOIC 8Pin.MOSFET Drivers.INTERSIL.ISL6612ACBZ;EE-A061931;14S966120 0;TWN	125	56.1	92.9	

**Note(\*):**

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.
3. **Judgment Criteria:**
  - **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
  - **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
  - **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.